

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Universal serial bus interfaces for data and power –  
Part 1-2: Common components – USB Power Delivery specification**

**Interfaces de bus universel en série pour les données et l'alimentation  
électrique –  
Partie 1-2: Composants communs – Spécification de l'alimentation électrique  
par port USB**

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IEC Secretariat  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland  
Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

USB Implementers Forum, Inc.  
3855 S.W. 153rd Drive  
Beaverton, OR 97003  
United States of America  
Tel. +1 503-619-0426  
[Admin@usb.org](mailto:Admin@usb.org)  
[www.usb.org](http://www.usb.org)

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## UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

### Part 1-2: Common components – USB Power Delivery specification

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International Standard IEC 62680-1-2 has been prepared by technical area 14: Interfaces and methods of measurement for personal computing equipment, of IEC technical committee 100: Audio, video and multimedia systems and equipment.

This third edition cancels and replaces the second edition published in 2017 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

This bilingual version (2019-03) corresponds to the monolingual English version, published in 2018-04.

The text of this International Standard is based on the following documents:

CDV	Report on voting
100/2968/CDV	100/3045/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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## INTRODUCTION

The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.1 and ECNs through 12 June 2017.

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# Universal Serial Bus Power Delivery Specification

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